

Memory Product Specification

DK.02GAK.F9QK2

2GB(1GB 128M x 64Bit x 2pcs) Kit

DDR3-1600MHz CL9 Overclocking Unbuffered DIMM

Description:

The overclocking unbuffered Module is a kit of two 128M x 64bit of 1GB DDR3-1600MHz CL9-9-9-27 at 1.65v Memory Module.

The Module base on eight 128M x 8-bit DDR3 FBGA SDRAM components.

The SPDs are programmed to JEDEC standard latency DDR3-1333MHz of CL9-9-9-24 at 1.5v.

Memory Module intended for mounting into 240-pin edge connector sockets.

The electrical and mechanical specifications are as follows:

Features:

- DDR3 Speed Grade : 1333Mbps
- Organization
 - 128M words × 64 bits, 1 rank
- Mounting 8 pieces of 1G bits DDR3 SDRAM sealed in FBGA
- Package: 240-pin socket type dual in line memory module (DIMM)
 - PCB height: 1.181 inch (30.0mm)
 - Lead-free (RoHS compliant)
- Power supply: VDD = 1.5V ± 0.075V
- Eight internal banks for concurrent operation (components)
- Interface: SSTL_15
- Burst lengths (BL): 8 and 4 with Burst Chop (BC)
- /CAS Latency (CL): 6, 7, 8, 9
- /CAS write latency (CWL): 5, 6, 7
- Precharge: auto precharge option for each burst access
- Refresh: auto-refresh, self-refresh
- Refresh cycles
 - Average refresh period
 - 7.8μs at 0°C ≤ TC ≤ +85°C
 - 3.9μs at +85°C < TC ≤ +95°C
- Operating case temperature range
 - TC = 0°C to +95°C

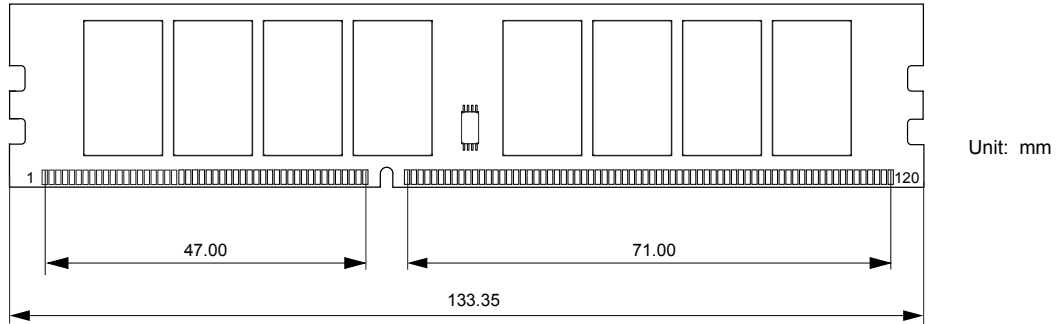
Overclocking Datasheet w/ Intel XMP:

- Active Heatspreader
- DDR3 Speed Grade : 1600Mbps
- Power supply: VDD voltage : 1.65v
VDDQ voltage : 1.65v
- CAS latency : CL9-9-9-27
- Bandwidth : 12800MB/s
- Serial presence detect with EEPROM.
- PCB height : 2.073 inch(52.65mm) w/ heatsink.
- RoHS Compliant
- Application : Gaming player

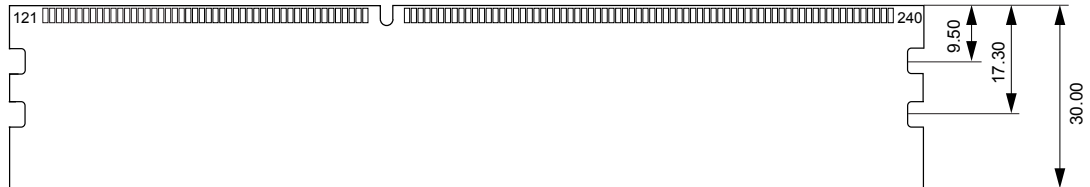


Dimensions

Front side



Back side



W/ Heatsink Assembly Dimensions



Retail Package

